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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re application of

: Confirmation No. 6334

Koji MISHIMA et al.

: Attorney Docket No. 2003_1305

Serial No. 10/660,483

: Group Art Unit 1742

Filed September 12, 2003

: Examiner William T. Leader

METHOD AND APPARATUS FOR PLATING
SUBSTRATE WITH COPPER

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975

Sir:

In response to the Office Action of March 27, 2006, please amend the above-referenced
U.S. patent application as follows: